

TL022C, TL022M DUAL LOW-POWER OPERATIONAL AMPLIFIERS

SLOS076 – SEPTEMBER 1973 – REVISED SEPTEMBER 1990

- Very Low Power Consumption
- Power Dissipation With ± 2 -V Supplies
170 μ W Typ
- Low Input Bias and Offset Currents
- Output Short-Circuit Protection
- Low Input Offset Voltage
- Internal Frequency Compensation
- Latch-Up-Free Operation
- Popular Dual Operational Amplifier Pinout

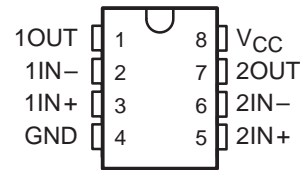
**TL022M IS NOT RECOMMENDED FOR
NEW DESIGNS**

description

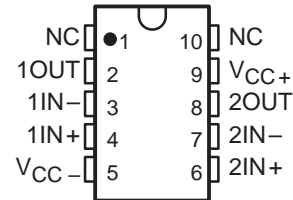
The TL022 is a dual low-power operational amplifier designed to replace higher power devices in many applications without sacrificing system performance. High input impedance, low supply currents, and low equivalent input noise voltage over a wide range of operating supply voltages result in an extremely versatile operational amplifier for use in a variety of analog applications including battery-operated circuits. Internal frequency compensation, absence of latch-up, high slew rate, and output short-circuit protection assure ease of use.

The TL022C is characterized for operation from 0°C to 70°C. The TL022M is characterized for operation over the full military temperature range of -55°C to 125°C.

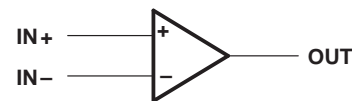
TL022M . . . JG PACKAGE
TL022C . . . D OR P PACKAGE
(TOP VIEW)



TL022M . . . U PACKAGE
(TOP VIEW)



symbol (each amplifier)



AVAILABLE OPTIONS

T _A	V _{IO} max AT 25°C	PACKAGE			
		SMALL OUTLINE (D)	CERAMIC DIP (JG)	PLASTIC DIP (P)	CERAMIC FLAT PACK (U)
0°C to 70°C	5 mV	TL022CD	—	TL022CP	—
-55°C to 125°C	5 mV	—	TL022MJG	—	TL022MU

The D package is available taped and reeled. Add the suffix R to the device type (i.e. TL022CDR).

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SLOS076 – SEPTEMBER 1973 – REVISED SEPTEMBER 1990

schematic



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

	TL022C	TL022M	UNIT
Supply voltage, V_{CC+} (see Note 1)	18	22	V
Supply voltage, V_{CC-} (see Note 1)	-18	-22	V
Differential input voltage (see Note 2)	± 30	± 30	V
Input voltage (any input, see Notes 1 and 3)	± 15	± 15	V
Duration of output short circuit (see Note 4)	unlimited	unlimited	
Continuous total dissipation	See Dissipation Rating Table		
Operating free-air temperature range	0 to 70	-55 to 125	$^{\circ}\text{C}$
Storage temperature range	-65 to 150	-65 to 150	$^{\circ}\text{C}$
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds	JG or U package	300	$^{\circ}\text{C}$
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	D or P package	260	$^{\circ}\text{C}$

- NOTES: 1. All voltage values, unless otherwise noted, are with respect to the midpoint between V_{CC+} and V_{CC-} .
 2. Differential voltages are at IN+ with respect to IN- .
 3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
 4. The output may be shorted to ground or either power supply. For the TL022M only, the unlimited duration of the short circuit applies at (or below) 125 $^{\circ}\text{C}$ case temperature or 75 $^{\circ}\text{C}$ free-air temperature.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^{\circ}\text{C}$ POWER RATING	DERATING FACTOR	DERATE ABOVE T_A	$T_A = 70^{\circ}\text{C}$ POWER RATING	$T_A = 125^{\circ}\text{C}$ POWER RATING
D	680 mW	5.8 mW/ $^{\circ}\text{C}$	33 $^{\circ}\text{C}$	464 mW	—
JG	680 mW	8.4 mW/ $^{\circ}\text{C}$	69 $^{\circ}\text{C}$	672 mW	210 mW
P	680 mW	8.0 mW/ $^{\circ}\text{C}$	65 $^{\circ}\text{C}$	640 mW	—
U	675 mW	5.4 mW/ $^{\circ}\text{C}$	25 $^{\circ}\text{C}$	432 mW	135 mW



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recommended operating conditions

	MIN	MAX	UNIT
Supply voltage, V_{CC+}	5	15	V
Supply voltage, V_{CC-}	-5	-15	V

electrical characteristics at specified free-air temperature, $V_{CC\pm} = \pm 15$ V (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	TL022C			TL022M			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO} Input offset voltage	$V_O = 0$, $R_S = 50 \Omega$	25°C	1	5	1	5	mV	
		Full range		7.5		6		
I_{IO} Input offset current	$V_O = 0$	25°C	15	80	5	40	nA	
		Full range		200		100		
I_{IB} Input bias current	$V_O = 0$	25°C	100	250	50	100	nA	
		Full range		400		250		
V_{ICR} Common-mode input voltage range		25°C	±12	±13	±12	±13	V	
		Full range	±12		±12			
$V_{O(PP)}$ Maximum peak-to-peak output voltage swing	$R_L = 10 \text{ k}\Omega$	25°C	20	26	20	26	V	
	$R_L \geq 10 \text{ k}\Omega$	Full range	20		20			
A_{VD} Large-signal differential voltage amplification	$R_L \geq 10 \text{ k}\Omega$, $V_O = \pm 10$ V	25°C	60	80	72	86	dB	
		Full range	60		66			
B_1 Unity-gain bandwidth		25°C	0.5		0.5		MHz	
CMRR Common-mode rejection ratio	$V_{IC} = V_{ICRmin}$, $R_S = 50 \Omega$	25°C	60	72	60	72	dB	
		Full range	60		60			
k_{SVS} Supply voltage sensitivity ($\Delta V_{IO}/\Delta V_{CC}$)	$V_{CC} = \pm 9$ V to ± 15 V, $R_S = 50 \Omega$	25°C	30	200	30	150	$\mu\text{V/V}$	
		Full range		200		150		
V_n Equivalent input noise voltage	$A_{VD} = 20$ dB, $B = 1$ Hz,	25°C	50		50		nV/Hz	
I_{OS} Short-circuit output current		25°C	±6		±6		mA	
I_{CC} Supply current (both amplifiers)	$V_O = 0$, No load	25°C	130	250	130	250	μA	
		Full range		250		250		
P_D Total dissipation (both amplifiers)	$V_O = 0$, No load	25°C	3.9	7.5	3.9	6	mW	
		Full range		7.5		6		

† All characteristics are measured under open-loop conditions with zero common-mode input voltage unless otherwise specified. Full range for TL022C is 0°C to 70°C and for TL022M is -55°C to 125°C.

operating characteristics, $V_{CC\pm} = \pm 15$ V, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_r Rise time	$V_I = 20$ mV, $R_L = 10 \text{ k}\Omega$, $C_L = 100$ pF, See Figure 1		0.3		μs
Overshoot factor			5%		
SR Slew rate at unity gain	$V_I = 10$ V, $R_L = 10 \text{ k}\Omega$, $C_L = 100$ pF, See Figure 1		0.5		V/ μs



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PARAMETER MEASUREMENT INFORMATION

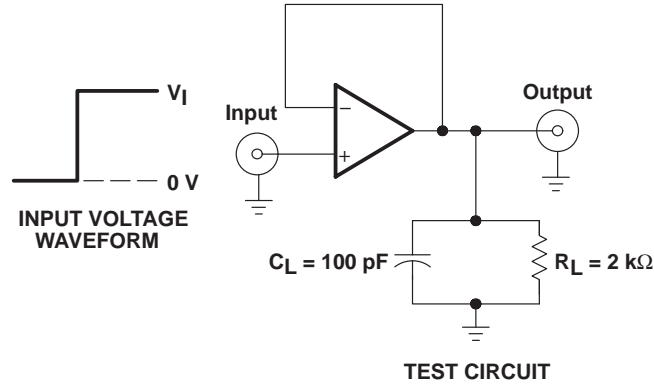


Figure 1. Rise Time, Overshoot Factor, and Slew Rate

TYPICAL CHARACTERISTICS

TOTAL POWER DISSIPATION
vs
SUPPLY RATE

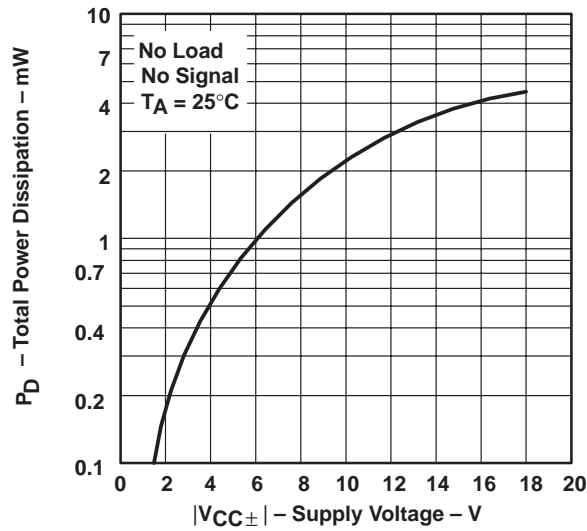


Figure 2

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL022CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL022CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL022CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL022CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL022CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL022CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL022CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL022CPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL022CPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL022CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL022CPSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL022CDR	SOIC	D	8	2500	340.5	338.1	20.6
TL022CPSR	SO	PS	8	2000	367.0	367.0	38.0

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001 variation BA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



4211283-2/E 08/12

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PS (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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